IN THE CLAIMS:

Please cancel claims 12-20 and amend claims 21, 23 and 25 as follows:

1. (Original) A device having:

a first wafer having a first area and a second area opposed to each other with a first scribe area in-between, wherein a first mechanical element and a first pad are formed in said first area and a second mechanical element and a second pad are formed in said second area, and

a second wafer which selas said first mechanical element and said second mechanical element with a prescribed space over each of said first mechanical element and said second mechanical element formed in said first wafer, wherein:

said second wafer is provided with an aperture having a first side and a second side opposed to said first side, for exposing said first pad and said second pad, and

said aperture is so positioned that said first pad is placed between said first side and said first scribe area and said second pad is placed between said second side and said first scribe area.

2. (Original) The device according to Claim 1, wherein:

said first wafer has a second scribe area and a third scribe area,

said aperture has a third side crossing said first side and said second side and a fourth side opposed to said third side,

the fourth side of said aperture is placed between said second scribe area, said first pad and said second pad, and

the third side of said aperture is arranged to be placed between said third scribe area, said first pad and said second pad.

3. (Original) The device according to Claim 1, wherein:

said first wafer has:

a second scribe area,

a third area opposed to said first area with said second scribe area in-between, and

a fourth area opposed to said second area with said second scribe area in-between and opposed to said third area with said first scribe area in-between, wherein:

a third mechanical element and a third pad are formed in said third area,

a fourth mechanical element and a fourth pad are formed in said fourth area,

said aperture is so arranged as to expose said third pad and said fourth pad, and

said aperture is so arranged as to place said third pad between said first side and said first scribe area and to place said fourth pad between said second side and said first scribe area.

4. (Original) The device according to Claim 3, wherein:

said aperture has a third side crossing said first side and said second side and a fourth side opposed to said third side,

said aperture is so arranged as to place said first and second pads between said third side and said second scribe area and to place said third and fourth pad between said fourth side and said second scribe area.

5. (Original) The device according to Claim 1, wherein:

said first wafer further has a first laminate film formed between said first pad and said first mechanical element in said first area and a second laminate film formed between said second pad and said second mechanical element in said second area, and

said second wafer seals said first and second mechanical elements by being adhered to said first laminate film and said second laminate film.

6. (Original) The device according to Claim 1, wherein:

said first wafer has a silicon substrate and a transistor formed over the silicon substrate.

7. (Original) The device according to Claim 1, wherein:

said first mechanical element has a movable object having a movable part and a fifth pad formed underneath said movable object.

8. (Original) The device according to Claim 1, wherein:

said first wafer further has second through fifth scribe areas,

said first area is surrounded by said first, second, third and fourth scribe areas, and

said second area is surrounded by said first, second, third and fifth scribe

areas.

9. (Original) The device according to Claim 8, wherein:

said first area is made a first chip by cutting said first, second, third and fourth scribe areas, and

said second area is made a second chip by cutting said first, second, third and fifth scribe areas.

10. (Original) The device according to Claim 3, wherein:

said first wafer further has third through sixth scribe areas,

said first area is surrounded by said first, second, third and fourth scribe areas,

said second area is surrounded by said first, second, third and fifth scribe areas,

said third area is surrounded by said first, second, fourth and sixth scribe areas, and

said fourth area is surrounded by said first, second, fifth and sixth scribe areas.

11. (Original) The device according to Claim 10, wherein:

said first area is made a first chip by cutting said first, second, third and fourth scribe areas,

said second area is made a second chip by cutting said first, second, third and fifth scribe areas,

said third area is made a third chip by cutting said first, second, fourth and sixth scribe areas, and

said fourth area is made a fourth chip by cutting said first, second, fifth and sixth scribe areas.

12-20 (Cancelled)

21. (Currently Amended) A device having:

a substrate having a first side, a second side opposed to said first side, a third side crossing said first and second sides, and a fourth side opposed to said third side,

a first pad and a second pad formed over said substrate,

a mechanical element formed over said substrate, and

a sealing layer which seals said mechanical element and has a first aperture opening said first pad and said second pad together, wherein:

said first aperture is so arranged as to place said first pad and said second pad between a fifth side of said first aperture and the first side of said substrate, and a sixth side which crosses said fifth side of said first aperture and comes into contact with the first side of said substrate is so arranged as to be placed between the third side of said substrate and said first pad and said second pad.

22. (Original) The device according to Claim 21 wherein:

said first aperture is arranged in a corner formed between the first side and fourth side of said substrate.

23. (Currently Amended) The device according to Claim 21 wherein:

said substrate further has a ~~second pad~~ third pad and a fourth pad,

said sealing layer further has a second aperture opening said third pad and said fourth pad together, and

said second aperture is so arranged as to place said ~~second pad~~ third pad and said fourth pad between a seventh side of said second aperture and the second side of said substrate, and an eighth side which crosses said seventh side of said second aperture and comes into contact with the second side of said substrate is so arranged as to be placed between the fourth side of said substrate and said ~~second pad~~ third and fourth pads.

24. (Original) The device according to Claim 23 wherein:

said first aperture is arranged in a corner formed between the first side and fourth side of said substrate, and

said second aperture is arranged in a corner formed between the second side and third side of said substrate.

25. (Currently Amended) The device according to Claim 23 wherein:

said substrate further has a ~~third pad and a fourth pad~~ fifth pad, a sixth pad, a seventh pad and a eighth pad,

said sealing layer further has a third aperture and a fourth aperture,

said third aperture is so arranged as to place said third pad between a ninth

side of said third aperture and the third side of said substrate, a tenth side which crosses said ninth side of said third aperture and comes into contact with the third side of said substrate is placed between the second side of said substrate and said third pad,

said fourth aperture is so arranged as to place said fourth pad between an eleventh side of said fourth aperture and the fourth side of said substrate, and a twelfth side which crosses said eleventh side of said fourth aperture and comes into contact with the fourth side of said substrate is so arranged as to be placed between the first side of said substrate and said second pad.

26. (Original) The device according to Claim 25, wherein:

said first aperture is arranged in a corner formed between the first side and fourth side of said substrate,

said second aperture is arranged in a corner formed between the second side and third side of said substrate,

said third aperture is arranged in a corner formed between the third side and first side of said substrate, and

said fourth aperture is arranged in a corner formed between the fourth side and second side of said substrate.